



US00D833990S

(12) **United States Design Patent**
Podubni

(10) **Patent No.:** **US D833,990 S**

(45) **Date of Patent:** **** Nov. 20, 2018**

- (54) **MODULAR CIRCUIT BOARD**
- (71) Applicant: **Tiny PCB, Inc.**, San Jose, CA (US)
- (72) Inventor: **Edward Podubni**, San Jose, CA (US)
- (73) Assignee: **TinyPCB, Inc.**
- (**) Term: **15 Years**
- (21) Appl. No.: **29/605,715**
- (22) Filed: **May 30, 2017**
- (51) **LOC (11) Cl.** **13-03**
- (52) **U.S. Cl.**
USPC **D13/182**
- (58) **Field of Classification Search**
USPC D13/182; 174/68.1, 250, 253, 255, 256;
318/567, 568.1; 361/600, 601, 718, 719,
361/720, 728, 736, 748, 751, 752, 760,
361/761, 807; 439/55, 65, 68, 76.1, 92,
439/93, 95
CPC H05K 3/00; H05K 3/30; H05K 3/301;
H05K 3/303; H05K 3/34; H05K 3/3405;
H05K 3/341; H05K 3/36; H05K 3/361;
H05K 3/363; H05K 3/40; H05K 7/14;
H05K 7/1422; H05K 7/00; H05K 1/18;
H05K 1/02; H05K 1/181; H05K 1/182;
H05K 1/183; H05K 1/184; H05K 1/189;
H05K 1/00
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

- 2,896,033 A * 7/1959 Hartz H01H 19/585
200/11 D
- 3,072,734 A * 1/1963 Fox H02B 1/043
174/254
- D279,670 S * 7/1985 Lukits D13/182
- 4,602,271 A * 7/1986 Dougherty, Jr. H01L 23/5385
257/697

- 4,715,928 A * 12/1987 Hamby H05K 3/4691
156/150
- D319,045 S * 8/1991 Hasegawa D13/182
- D319,629 S * 9/1991 Hasegawa D13/182
- D319,814 S * 9/1991 Hasegawa D13/182
- D397,093 S * 8/1998 Kim D13/182
- 5,895,967 A * 4/1999 Stearns H01L 23/3128
257/691
- D429,704 S * 8/2000 Kang D13/182
- 6,121,554 A * 9/2000 Kamikawa H05K 1/113
174/255
- D440,209 S * 4/2001 Kang D13/182
- D442,149 S * 5/2001 Kang D13/182
- D442,150 S * 5/2001 Kang D13/182
- D442,567 S * 5/2001 Kang D13/182
- D457,146 S * 5/2002 Yamamoto D13/182
- 6,418,030 B1 * 7/2002 Yamaguchi H01L 23/24
257/698
- 6,462,570 B1 10/2002 Price et al.
- D466,093 S * 11/2002 Ebihara D13/182
- D471,167 S * 3/2003 Ebihara D13/182

(Continued)

Primary Examiner — Elizabeth J Oswecki

(74) *Attorney, Agent, or Firm* — Cooley LLP

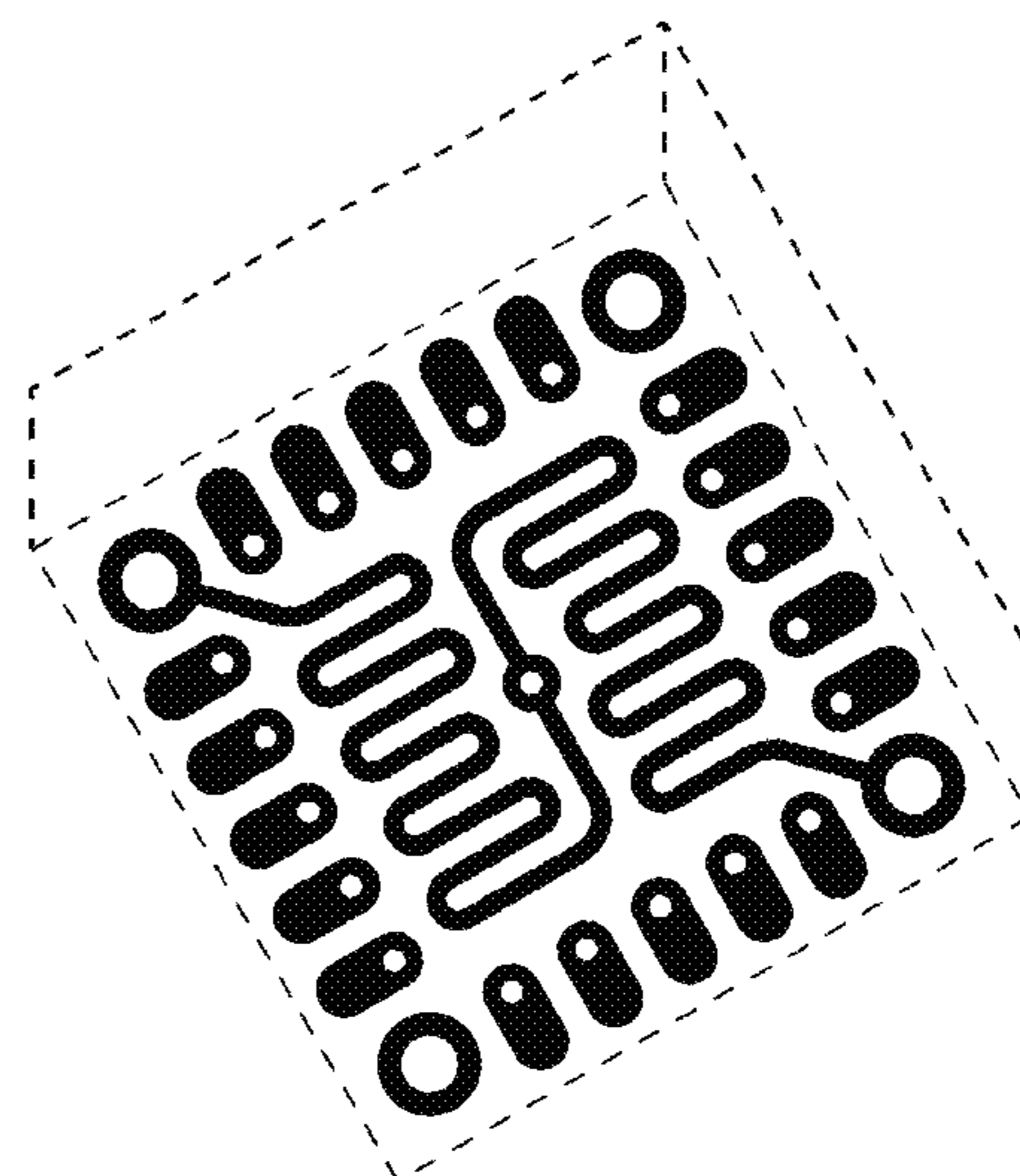
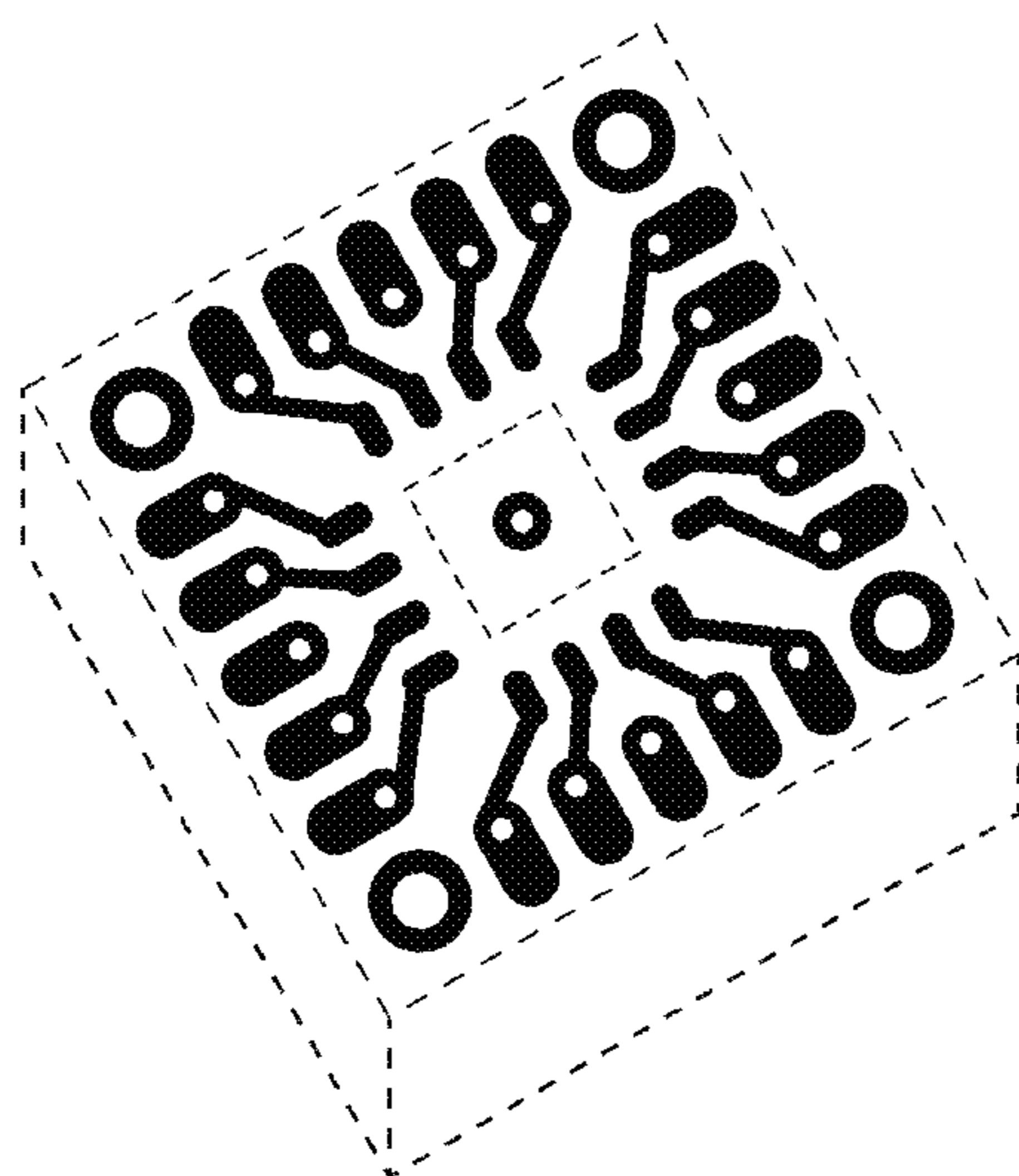
(57) **CLAIM**

The ornamental design for a modular circuit board, as shown and described.

DESCRIPTION

FIG. 1 is a top perspective view of a modular circuit board, showing my new design;
 FIG. 2 is a bottom perspective view thereof;
 FIG. 3 is a top view thereof;
 FIG. 4 is a bottom view thereof; and,
 FIG. 5 is a side view thereof, all other side views being a mirror image thereof.
 The broken lines shown in the drawings represent portions of the modular circuit board that form no part of the claimed design.

1 Claim, 5 Drawing Sheets



(56)

References Cited

U.S. PATENT DOCUMENTS

D474,773	S *	5/2003	Kondo	D13/182
D485,536	S *	1/2004	Dang	D13/182
6,936,916	B2 *	8/2005	Moxham	H01L 23/13 174/256
D552,048	S *	10/2007	He	D13/182
D556,158	S *	11/2007	Kong	D13/182
7,511,228	B2	3/2009	Yaung et al.		
D599,308	S *	9/2009	Blumberg, Jr.	D13/182
D605,613	S *	12/2009	Carter	D13/182
D639,756	S *	6/2011	Greene, Jr.	D13/182
D642,546	S *	8/2011	Greene, Jr.	D13/182
D645,039	S *	9/2011	Chen	D14/341
8,113,888	B2 *	2/2012	Carter	H01R 9/03 439/676
D676,004	S *	2/2013	Lyubachev	D13/182
D699,201	S *	2/2014	Petsch	D13/182
D768,115	S *	10/2016	Kazanchian	D13/182
D794,586	S *	8/2017	Takahashi	D13/182
D799,438	S *	10/2017	Takahashi	D13/182
D804,437	S *	12/2017	Kantor	D13/182
2009/0250246	A1	10/2009	Yaung et al.		

* cited by examiner

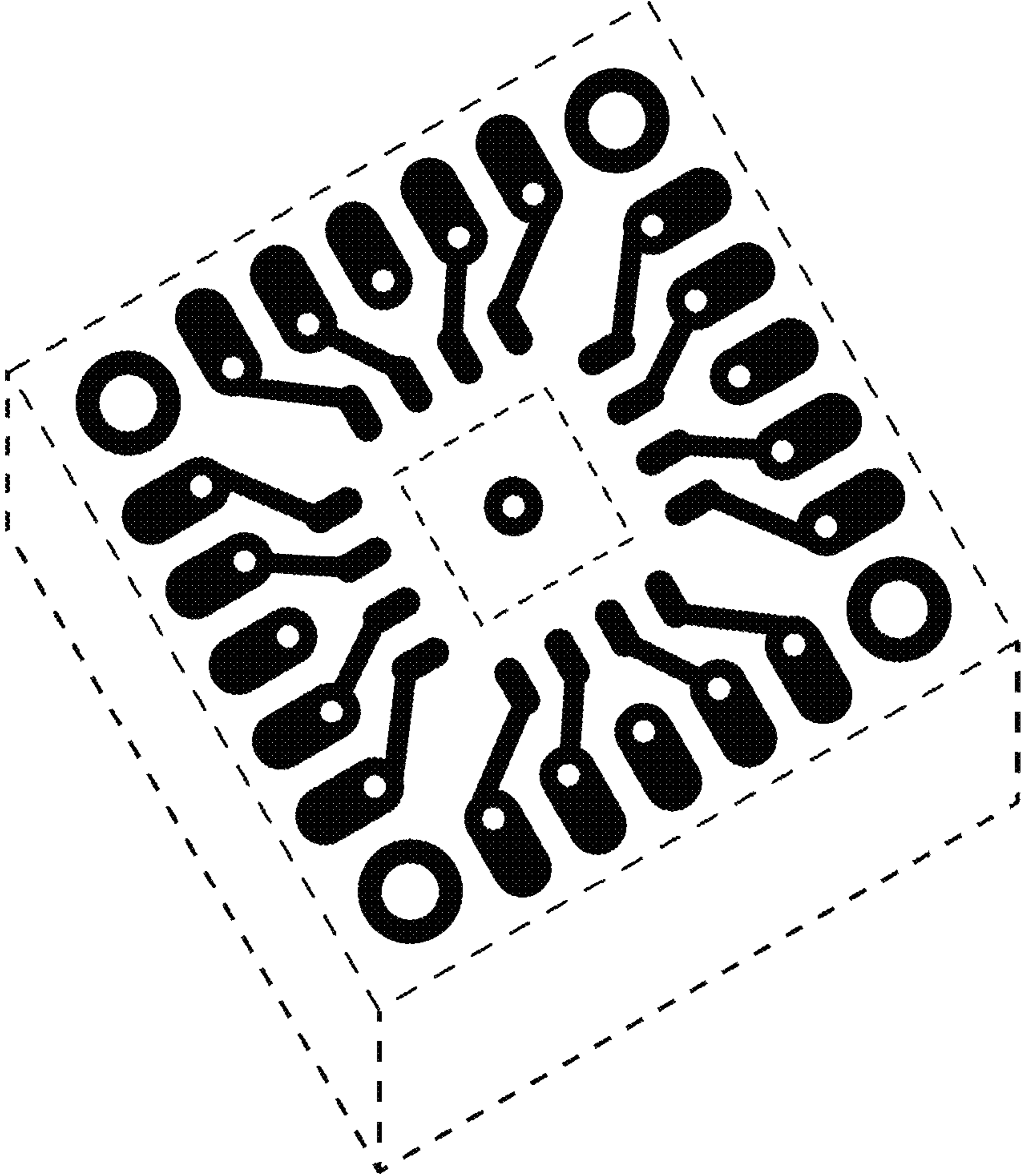


FIG. 1

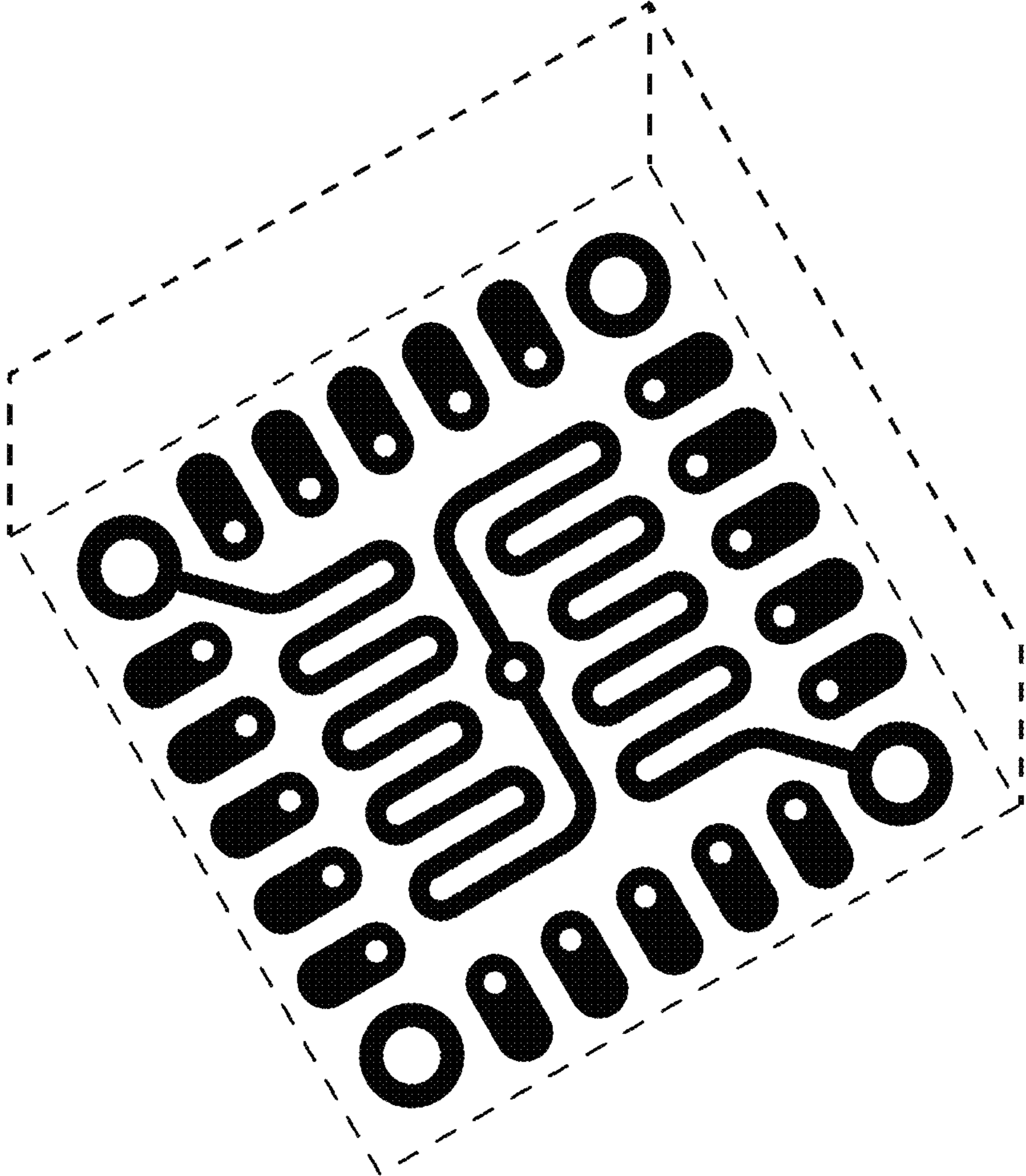


FIG. 2

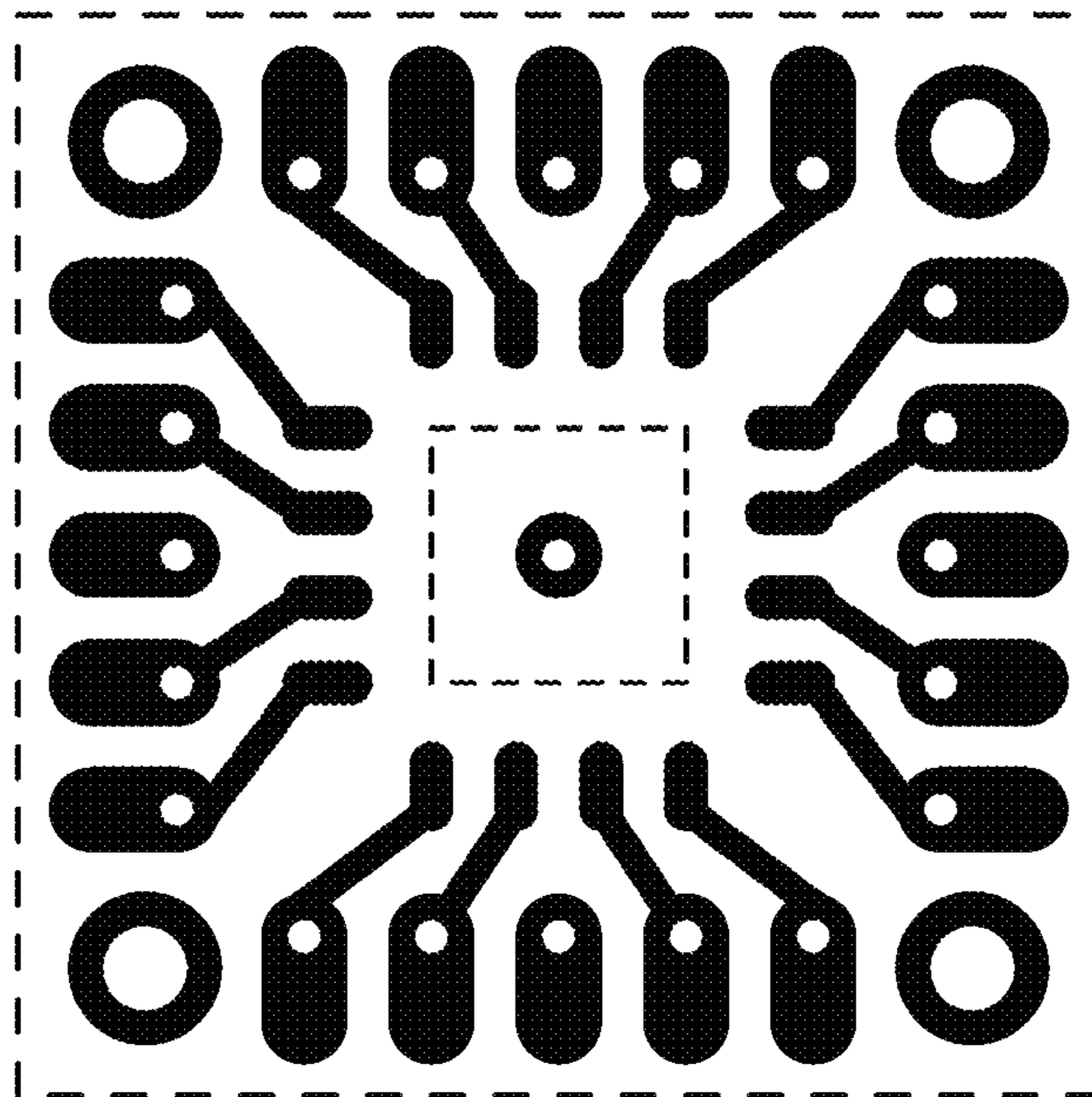


FIG. 3

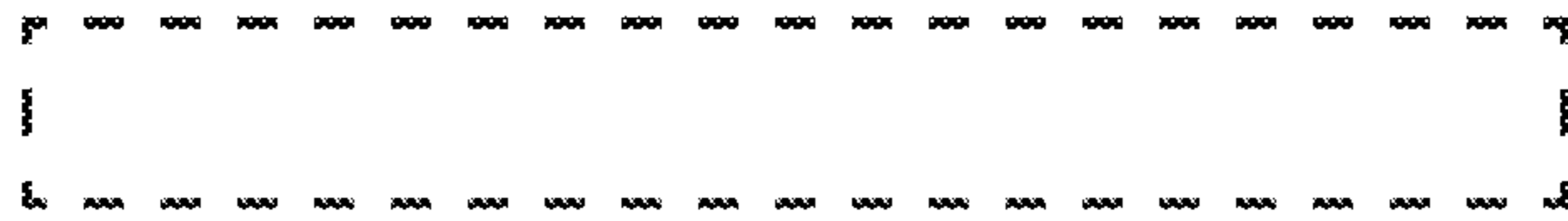


FIG. 5